PROJECT TITLE

MAJOR/ MINOR PROJECT SYNOPSIS

BACHELOR OF TECHNOLOGY

Information Technology

 ${\bf SUBMITTED~BY}$

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August 2008



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1 Introduction

The introduction part will be of 1 Page include the brief introduction about the project to be developed, technology used, field of project (if specialized one), any special technical terms about the project.

Rationale: Justification, why needed? (1-2 paragraph)

2 Objectives

Include 3-4 points of Objectives.

- 1. First Objective.
- 2. Second Objective.
- 3. Third Objective.
- 4. Fourth Objective.

3 Feasibility Study

This should not exceed 1 page it describe the very first step of software engineering i.e. feasibility study of the project that include the feasibility, need and significance of the project

4 Methodology/ Planning of work

It should not exceed 1 page. Research type, unit, methods, tools of data collection / analysis. Methodology will include the steps to be followed to achieve the objective of the project during the project development. See Figure 1 it shows the bitnami installation first step.



Figure 1: Example of the Image

5 Facilities required for proposed work

 $Software/Hardware\ required\ for\ the\ development\ of\ the\ project.\ It\ includes\ 1\ paragraph.$

6 References

- [1] M. Shell. (2007) IEEEtran webpage on CTAN. [Online]. Available: http://www.ctan.org/tex-archive/macros/latex_IEEEtran/
- [2] Y. Okada, K. Dejima, and T. Ohishi, "Analysis and comparison of PM synchronous motor and induction motor type magnetic bearings," IEEE Trans. Ind. Appl., vol. 31, pp. 1047–1053, Sep./Oct. 1995.
- [3] S. Zhang, C. Zhu, J. K. O. Sin, and P. K. T. Mok, "A novel ultrathin elevated channel low-temperature poly-Si TFT," IEEE Electron Device Lett., vol. 20, pp. 569–571, Nov. 1999.